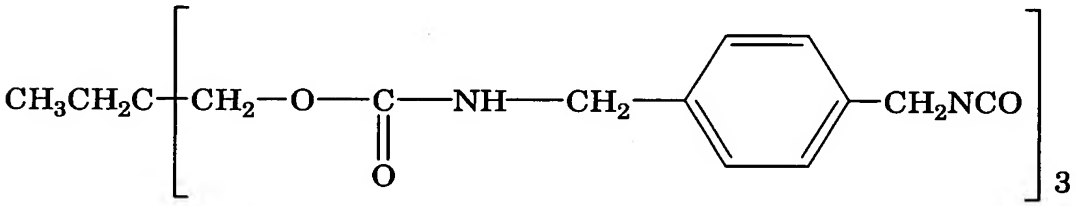
WHAT IS CLAIMED IS:

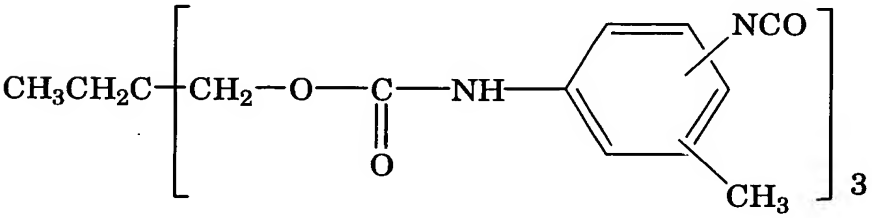
1. An adh sive composition comprising epoxy r sins (A), phenol resins (B), synthetic rubber (C), and microcapsules (D) including the hardening accelerator that has a core/shell structure in which a core part including the hardening accelerator is covered by a shell part formed with thermoplastic resins.

2. The adhesive composition according to Claim 1, wherein a shell part of the microcapsule (D) including the hardening accelerator is formed with a polyurea having an isocyanate compound using a triisocyanate compound (1) represented with following chemical formula (1), and a triisocyanate compound (2) represented with following chemical formula (2) at a percentage of a mixed molar ratio of (compound (1)) / (compound (2)) = 100 / 0 - 30 / 70 as a constituent element.

Chemical formula -- (1)

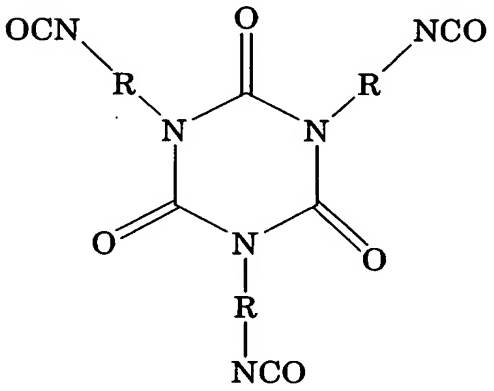


Chemical formula -- (2)



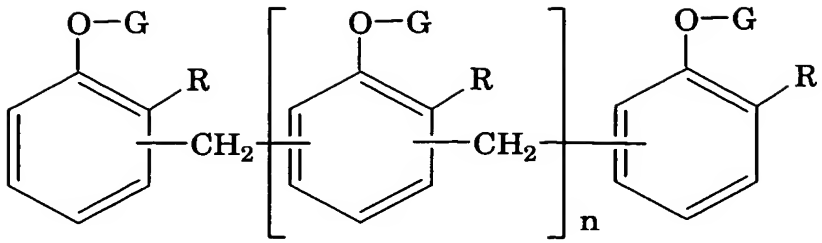
3. The adhesiv composition according to Claim 1, wherein a sh ll part of th microcapsule (D) including the hardening accelerator is formed with a polyurea having a triisocyanate compound (3) represented with following general formula (3) (where, R represents a bivalent organic group in the general formula (3)) as a constituent element.

Chemical formula -- (3)



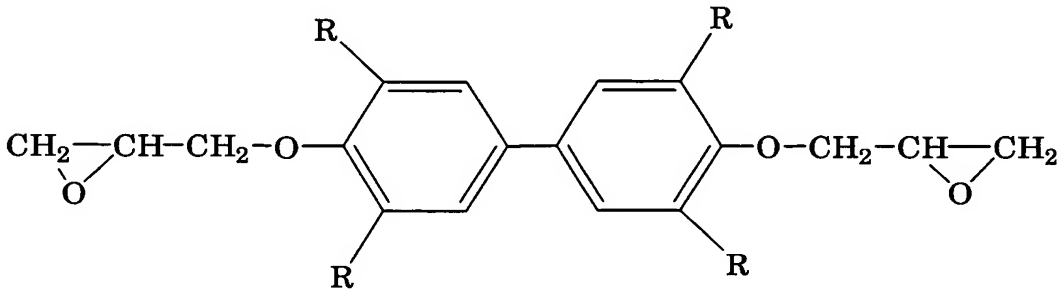
4. The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a novolak type epoxy resin represented with a following general formula (4) (where, G represents a glycidyl group, R represents -H or -CH_3, and n represents an integer of 1 or more in the general formula (4)) as a principal component.

Chemical formula -- (4)



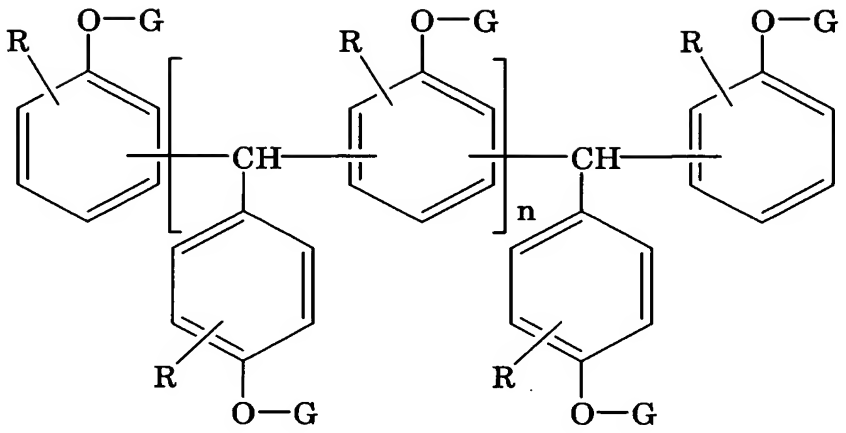
5. The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a biphenyl type epoxy resin represented with a following general formula (5) (where, R represents -H or -CH_3 in the general formula (5)) as a principal component.

Chemical formula -- (5)



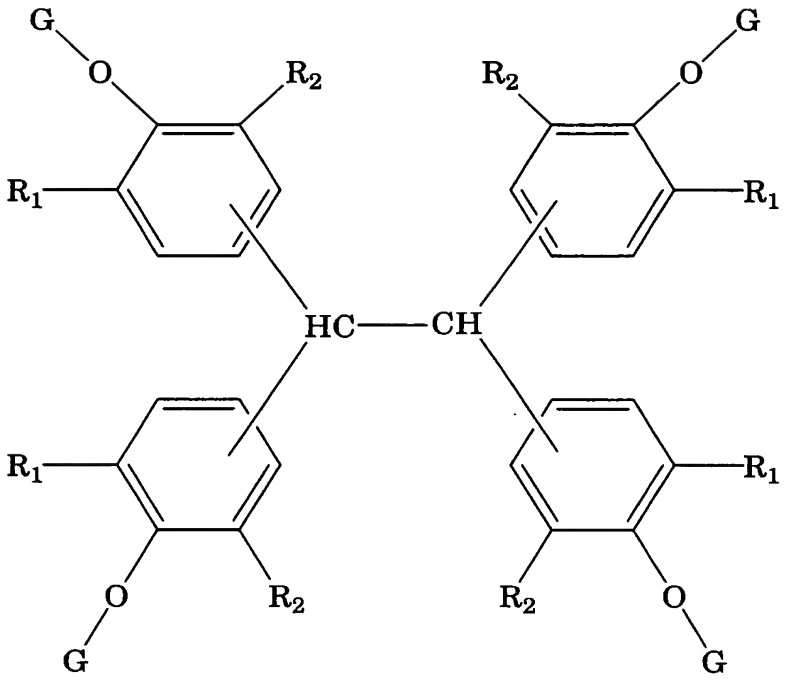
6. The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a tris hydroxyphenylmethane type epoxy resin represented with a following general formula (6) (where, G represents a glycidyl group, R represents -H or –CH_3, and n represents an integer of 0 or 1 or more in the general formula (6)) as a principal component.

Chemical formula -- (6)



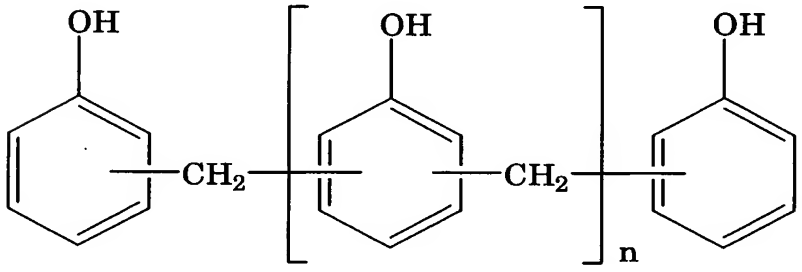
7. The adhesive composition according to Claim 1, wherein the epoxy resin (A) has a tetraphenylol ethane type epoxy resin represented with a following general formula (7) (where, G represents a glycidyl group, and R_1 and R_2 independently represent –H or -CH_3, respectively, in the general formula (7)) as a principal component.

Chemical formula -- (7)



8. The adhesive composition according to Claim 1, wherein the phenol resin (B) is a phenol novolak resin represented with a following general formula (8) (where, n represents an integer of 0 or 1 or more in the general formula (8)).

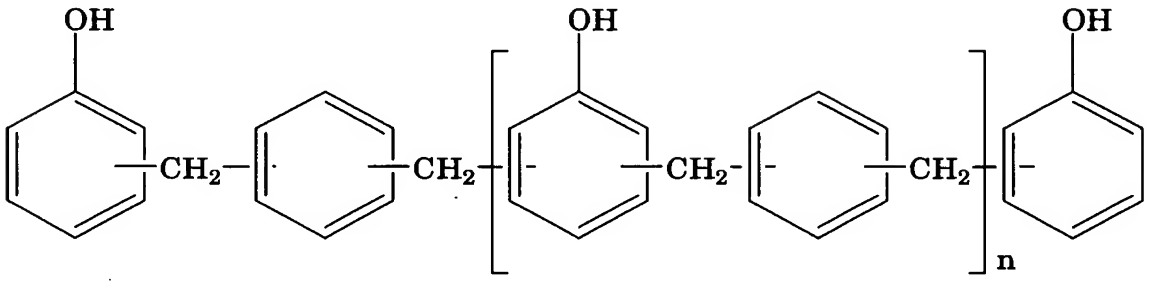
Chemical formula -- (8)



9. The adhesive composition according to Claim 1, wherein the phenol resin (B) is a phenol aralkyl resin represented with a

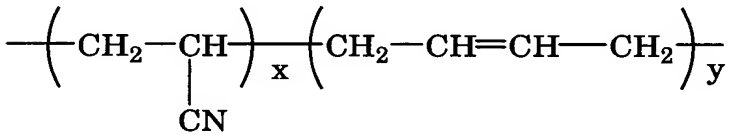
following general formula (9) (where, n represents an integer of 0 or 1 or more. in the general formula (9)).

Chemical formula -- (9)



10. The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is an acrylonitrile-butadiene rubber having a repeating unit represented with a following general formula (10) (where, x : y = 1 - 99 : 1 – 99 in the general formula (10)) as a principal constituent element.

Chemical formula -- (10)



11. The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is a carboxylated acrylonitrile-butadiene rubber having a repeating unit represented with a following general formula (11) (where, R represents -H or -CH_3, and x : y : z = 1 - 98 : 1 - 98 : 1 - 98 in the general formula (11)) as a principal constitu nt

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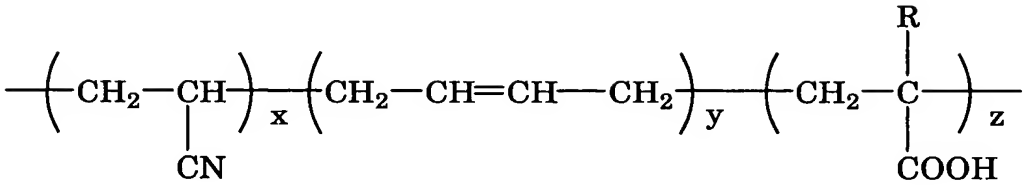
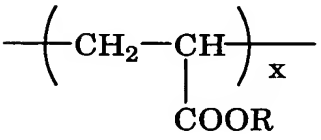
Ch mical formula -- (11)



12. The adhesive composition according to Claim 1, wherein the synthetic rubber (C) is a carboxylated acrylic rubber having a repeating unit represented with a following general formula (12) (where, R represents a monovalent organic group, and x represents an integer of 1 or more in the general formula (12)) as a principal constituent element.

Chemical formula -- (12)



13. The adhesive composition according to Claim 1, wherein inorganic fillers are further included.

14. An adhesive film being formed of the adhesive composition according to Claim 1.

15. A laminated adhesive film comprising the adhesive film according to Claim 14 and a pr ssur sensitiv adhesiv film.

16. An adhesiv film for di bonding using th adh sive film according to Claim 14 or 15.

17. A semiconductor apparatus wherein a semiconductor device is die-bonded using the adhesive film for die bonding according to Claim 16.